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| <b>PATENT ASSIGNMENT COVER SHEET</b> |
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| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT                     |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT                         |
| <b>CONVEYING PARTY DATA</b>   |                                    |
| <b>Name</b>   | <b>Execution Date</b>              |
| KEITH SANFREY   | 07/15/2015                         |
| <b>RECEIVING PARTY DATA</b>   |                                    |
| <b>Name:</b>  | PENNANT MOLDINGS, INC.             |
| <b>Street Address:</b>  | 12381 STATE ROUTE 22 EAST          |
| <b>City:</b>  | SABINA                             |
| <b>State/Country:</b>   | OHIO                               |
| <b>Postal Code:</b>   | 45169                              |
| <b>PROPERTY NUMBERS Total: 1</b>  |                                    |
| <b>Property Type</b>  | <b>Number</b>                      |
| <b>Application Number:</b>  | 16194686                           |
| <b>CORRESPONDENCE DATA</b>  |                                    |
| <b>Fax Number:</b>  | (614)227-2100                      |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> |                                    |
| <b>Phone:</b>   | 6142272000                         |
| <b>Email:</b>   | ipdocket@porterwright.com          |
| <b>Correspondent Name:</b>  | PORTER WRIGHT MORRIS & ARTHUR, LLP |
| <b>Address Line 1:</b>  | 41 SOUTH HIGH STREET               |
| <b>Address Line 2:</b>  | SUITES 2800-3200                   |
| <b>Address Line 4:</b>  | COLUMBUS, OHIO 43215               |
| <b>ATTORNEY DOCKET NUMBER:</b>  | 4011586-200961                     |
| <b>NAME OF SUBMITTER:</b>   | RICHARD M. MESCHER                 |
| <b>SIGNATURE:</b>   | /richard m. mescher/               |
| <b>DATE SIGNED:</b>   | 11/19/2018                         |
| <b>Total Attachments: 2</b>   |                                    |
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| source=SKM_C454e18111912044#page2.tif   |                                    |

## PATENT ASSIGNMENT

Whereas, I, **Keith Sanfrey**, having a mailing address of 1868 State Route 72 South, Sabina, OH 45169, have jointly invented certain new and useful improvements in inventions for a "**One-Piece Sheet-Metal Structure Formed With Clench Locked Corners**", for which we are contemporaneously filing a U.S. patent application (Porter, Wright, Morris & Arthur Docket No. 4011586-200961);

And whereas, **Pennant Moldings, Inc.**, having a mailing address of 12381 State Route 22 East, Sabina, OH 45169, is desirous of acquiring the entire right, title and interest in, to and under said invention and said patent application, any non-provisional applications, continuing applications, continuations-in-part, divisional applications, refiled or reissue applications made in the United States of America and all other Nations which may result from said invention and information disclosed in said application, and any and all patents which may be issued therefrom;

Now, therefore, in consideration of my employment agreement and other good and valuable consideration, the receipt of which is hereby acknowledged, I, **Keith Sanfrey**, do hereby sell, assign and transfer to **Pennant Moldings, Inc.**, the entire right, title and interest, in and to my inventions of new and useful designs in and to a "**One-Piece Sheet-Metal Structure Formed With Clench Locked Corners**", said application for patent, the inventions therein described, and all rights appurtenant thereto and in all applications related thereto, including each of the following: the right to apply for any utility or design patents for said invention in the United States of America and in any and all other nations, any and all other applications for patents on said invention including all divisional, renewal, substitute and continuation applications based in whole or in part upon said inventions or upon said applications or related thereto; any and all patents that may issue thereon in the United States and other Nations and any and all reissues, extensions, renewals, divisions, or continuations of patents granted for said inventions or upon said applications, to the full end of the term or terms for which said patent may be issued; and every priority or other right accorded by every international convention, treaty or agreement that is or may be predicated upon or arise from said invention, application and other applications or patent therefor, all to be held and enjoyed by **Pennant Moldings, Inc.**, and its successors and assigns, all the same as I would have held and enjoyed had this Assignment not been made.

I hereby authorize and grant the right to **Pennant Moldings, Inc.**, and its successors and assigns, to file and prosecute patent applications in any or all countries on all or any part of said inventions in my name or in the name of **Pennant Moldings, Inc.**, and its successors and assigns, or otherwise, as **Pennant Moldings, Inc.**, and its successors and assigns, may deem advisable under any international convention, treaty, or agreement or otherwise.

I hereby request and authorize the Commissioner of Patents and Trademarks of the United States and the empowered officials of all other countries to grant, issue and transfer any patent for said invention to **Pennant Moldings, Inc.** as assignee of the entire right, title and interests therein, in accordance with this instrument of assignment.

I hereby represent and warrant that there are no outstanding rights or interests inconsistent with the rights and interests granted herein; I covenant that I will not execute, grant, or transfer any rights or interests inconsistent herewith, I bind myself and my heirs, executors, administrators and legal representatives to execute and deliver to **Pennant Moldings, Inc.**, and its successors and assigns, any further documents or instruments and to perform any and all acts that may be deemed necessary to enable it, and its successors and assigns, to file applications for patents for said inventions in any country in which it may elect to file such application, and to vest in **Pennant Moldings, Inc.**, and its successors and assigns, the title herein conveyed and intended to so be, and to enable such title to be recorded in the United States and each nation in which each such application may be filed so that any patent issued thereon shall be issued to **Pennant Moldings, Inc.**, and its successors and assigns; and I further covenant and agree, for myself and my executors, administrators and legal representatives, that I and they will, upon request, communicate to **Pennant Moldings, Inc.**, and its successors and assigns, any facts relating to said inventions and the histories thereof, known to me or them and that I or they will testify as to the same in any proceeding, interference or litigation when requested to do so by **Pennant Moldings, Inc.**, and its successors and assigns.

Inventor:

**Keith Sanfrey**

Inventor's Signature:

Keith Sanfrey

Date Signed:

2/15/15

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